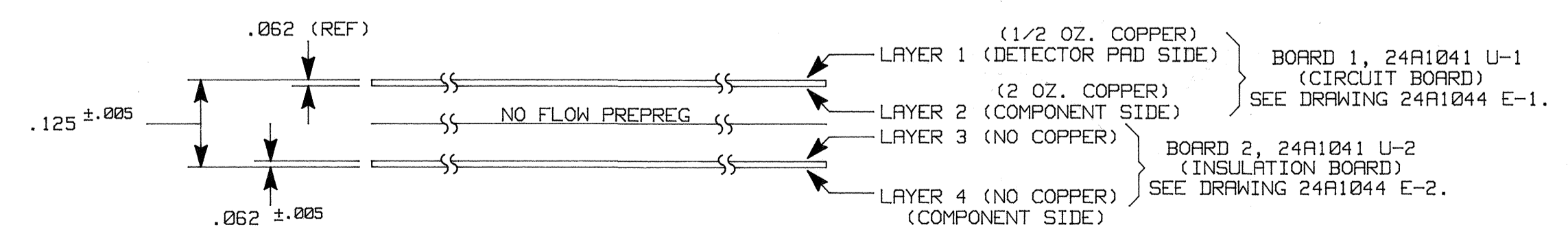


COMPONENT SIDE (LAYER 2) VIEW  
24A1041 U-1 a000886u1



NOTES:

- THIS DRAWING REPRESENTS THE ARTWORK TO MASK THE BOARD FOR TIN PLATING THE SMT CONNECTOR PADS.
- THIS IS A MULTILAYER BOARD CONSISTING OF FOUR LAYERS. BOARD MATERIAL IS EPOXY GLASS LAMINATE TYPE NEMA G10. FINISHED BOARD THICKNESS IS .125 +/- .005". BOARD SIZE IS 26.000"W X 10.460"H X 29.000"H +/- .030".
- ARTWORK TO BE PLOTTED ON GLASS FOR REGISTRATION ACCURACY.
- REFERENCE DRAWINGS:  
 24A1044 E-1 a000886e1 HOLE SCHEDULE - CIRCUIT BOARD  
 24A1044 E-2 a000886e2 ROUTING SCHEDULE - INSULATION BOARD  
 24A1044 M-1 a000886m1 BOARD OUTLINE

I:		TITLE		STAR TPC	
II:		DRAWN		STIRKKINEN	
III:		DATE		10/20/94	
DRAWN ON		CHECKED		DATE	
ACCOUNT NUMBER		APPROVED		DATE	
SERIAL NUMBER		ENGINEER		FRED BIESER	
DATE ISSUED		FILE NO.		a000886e3	
DATE RECD.		NO. RECD.		4	
DEL. TO		SCALE		NONE	
		UNIVERSITY OF CALIFORNIA		OFFICE OF ELECTRONICS ENGINEERING	
		LAWRENCE BERKELEY LABORATORY		24A1044 E-3	
		R12, E14		SHEET 3 OF 3	